

**■ ⚠ Caution (Storage and Operating Conditions)**

This product is designed for application in an ordinary environment (normal room temperature, humidity and atmospheric pressure). Do not use under the following conditions because all of these factors can deteriorate the product characteristics or cause failures and burn-out.

1. Corrosive gas or deoxidizing gas (Chlorine gas, Hydrogen sulfide gas, Ammonia gas, Sulfuric acid gas, Nitric oxide gas, etc.)

2. Volatile or flammable gas
3. Dusty conditions
4. Under vacuum, or under high or low pressure
5. Wet or humid locations
6. Places with salt water, oils, chemical liquids or organic solvents
7. Strong vibrations
8. Other places where similar hazardous conditions exist

**■ ⚠ Caution (Others)**

Be sure to provide an appropriate fail-safe function on your product to prevent secondary damages that may be caused by the abnormal function or the failure of our product.

**■ Notice (Storage and Operating Conditions)**

To keep solderability of product from declining, the following storage condition is recommended.

1. Storage Condition: Temperature -10 to +40°C  
Humidity less than 75%RH (not dewing condition)
2. Storage Term: Use this product within 6 months after delivery by first-in and first-out stocking system.

3. Handling After Unpacking: After unpacking, reseal product promptly or store it in a sealed container with a drying agent.
4. Storage Place: Do not store this product in corrosive gas (Sulfuric acid gas, Chlorine gas, etc.) or in direct sunlight.

**■ Notice (Rating)**

Use this product within the specified temperature range. Higher temperature may cause deterioration of the characteristics or the material quality of this product.

**■ Notice (Soldering and Mounting)**

Please notice as shown below when you mount this product.

1. This product is using the solder of about 240°C of melting points. Please perform soldering on a condition not melt the solder in resin head (260°C, less than 10 seconds and more than 8mm in full length of the product).  
When I am the worst, heat reaches the element part from a lead terminal part, and a solder of our product element region melts it, and there are fear of break of wire, or short circuit.
2. Please do a quality rating enough by a real machine when bonding, the resin molding, and the resin curing, etc. are processed to this product. and, please use it after confirming it is unquestionable.  
Especially, please do not process it under the high temperature and the high pressure.

The stress occurs because of the amount, the resin thickness, bias, and the temperature change of the fabricating materials (bonding material, molding resin, and curing material etc.)

And, there is a possibility to generate the crack and the characteristic degradation by the stress.

3. If strong tension against a lead or aggressiveness pressure strong against a resin part is applied, a resin part and an internal element will break or crack.  
In addition, the risk of the break or crack increases more because resin might soften in a high temperature, the pressurized state. Please avoid use in the state where it was pressurized.
4. Do not touch the resin head directly by solder iron.  
It may cause the melt of solder in resin head.

**■ Notice (Handling)**

1. The ceramic element of this product is fragile, and care must be taken not to load an excessive press-force or not to give a shock at handling. Such forces may cause cracking or chipping.

2. Do not apply an excessive force to the lead. Otherwise, it may cause junction between lead and element to break or crack. Holding element by side lead wire is recommended when lead wire is bent or cut.